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10 713 852

~~Filed Herewith~~ 11/14/03

**Aslı B. Ucok, et al.**

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| Examiner<br>Signature | Jasmine Clark | Date<br>Considered | 12/09/04 |
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11/14/03

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|  |                       | Applicati n Number  | 10 713 852             |                        |              |
|  |                       | Filing Date   | Filed Hewlett-11/14/03 |                        |              |
|  |                       | First Named Inventor  | Asli B. Ucok           |                        |              |
|  |                       | Group Art Unit  | 2815                   |                        |              |
|  |                       | Examiner Name   | Jasmine clark          |                        |              |
| Sheet  | 2                     | of  | 2                      | Attorney Docket Number | UOM 0319 PUS |
| <b>OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS</b>  |                       |   |                        |                        |              |
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| Examiner<br>Signature | Jasmine clark | Date<br>Consid red | 12/08/04 |
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